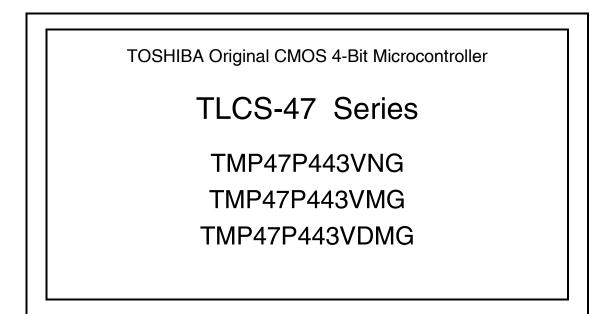
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Document Change Notification

The purpose of this notification is to inform customers about the launch of the Pb-free version of the device. The introduction of a Pb-free replacement affects the datasheet. Please understand that this notification is intended as a temporary substitute for a revision of the datasheet.

Changes to the datasheet may include the following, though not all of them may apply to this particular device.

1. Part number

Example: TMPxxxxxF TMPxxxxxFG

All references to the previous part number were left unchanged in body text. The new part number is indicated on the prelims pages (cover page and this notification).

2. Package code and package dimensions

Example: LQFP100-P-1414-0.50C LQFP100-P-1414-0.50F

All references to the previous package code and package dimensions were left unchanged in body text. The new ones are indicated on the prelims pages.

3. Addition of notes on lead solderability

Now that the device is Pb-free, notes on lead solderability have been added.

4. RESTRICTIONS ON PRODUCT USE

The previous (obsolete) provision might be left unchanged on page 1 of body text. A new replacement is included on the next page.

5. Publication date of the datasheet

The publication date at the lower right corner of the prelims pages applies to the new device.

1. Part number

2. Package code and dimensions

Previous Part Number (in Body Text)	Previous Package Code (in Body Text)	New Part Number	New Package Code	OTP
TMP47P443VN	P-SDIP28-400-1.78	TMP47P443VNG	SDIP28-P-400-1.78	_
TMP47P443VM	P-SOP28-450-1.27	TMP47P443VMG	SOP28-P-450-1.27B	—
TMP47P443VDM	P-SSOP30-56-0.65	TMP47P443VDMG	SSOP30-P-56-0.65	—

*: For the dimensions of the new package, see the attached Package Dimensions diagram.

3. Addition of notes on lead solderability

The following solderability test is conducted on the new device.

Lead solderability of Pb-free devices (with the G suffix)

Test	Test Conditions	Remark
Solderability	 (1) Use of Lead (Pb) solder bath temperature = 230°C dipping time = 5 seconds the number of times = once use of R-type flux (2) Use of Lead (Pb)-Free solder bath temperature = 245°C dipping time = 5 seconds the number of times = once use of R-type flux 	Leads with over 95% solder coverage till lead forming are acceptable.

4. RESTRICTIONS ON PRODUCT USE

The following replaces the "RESTRICTIONS ON PRODUCT USE" on page 1 of body text.

RESTRICTIONS ON PRODUCT USE

20070701-EN

• The information contained herein is subject to change without notice.

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- For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance/Handling Precautions.

5. Publication date of the datasheet

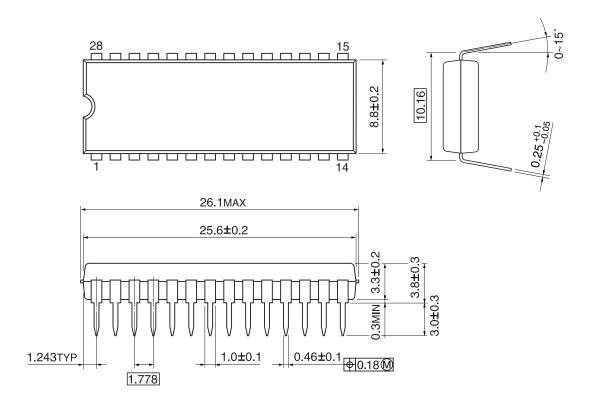
The publication date of this datasheet is printed at the lower right corner of this notification.

(Annex)

Package Dimensions

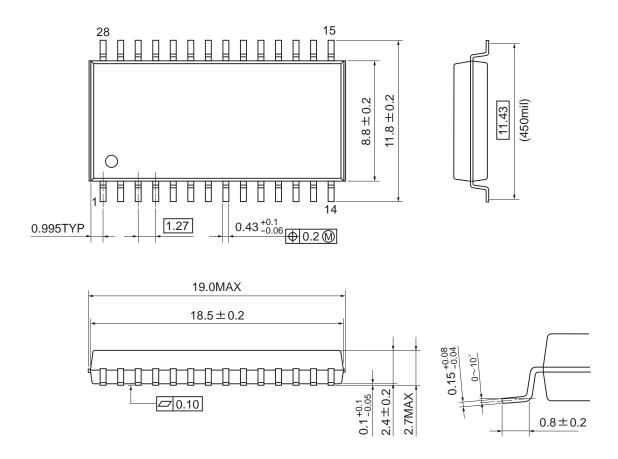
SDIP28-P-400-1.78

Unit: mm



SOP28-P-450-1.27B

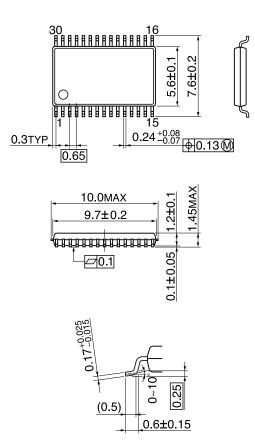
Unit: mm



Note: Palladium plated

SSOP30-P-56-0.65

Unit: mm



CMOS 4-Bit Microcontroller

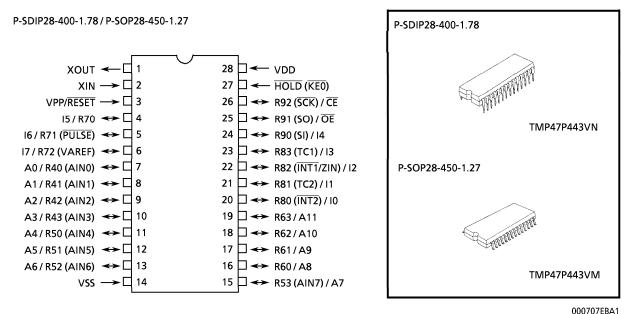
TMP47P443VN TMP47P443VM TMP47P443VDM

The TMP47P443V is the system evaluation LSI of TMP47C243/443 with a 32 Kbit one-time PROM. The TMP47P443V programs / verifies using an adapter socket to connect with PROM programmer, as it is in TMM27256AD.

In addition, the TMP47P443V and the TMP47C243/443 are pin compatible. The TMP47P443V operates as the same as the TMP47C243/443 by programming to the internal PROM.

Part No.	ROM	RAM	Rackage	Adapter Socket	
TMP47P443VN	ОТР		P-SDIP28-400-1.78	BM11100	
TMP47P443VM	OTP	• · · ·	256 x 4-bit	P-SOP28-450-1.27	BM11101
TMP47P443VDM	4096 x 8-bit		P-SSOP30-56-0.65	BM11115	

Pin Assignment (Top View)



For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance / Handling Precautions.

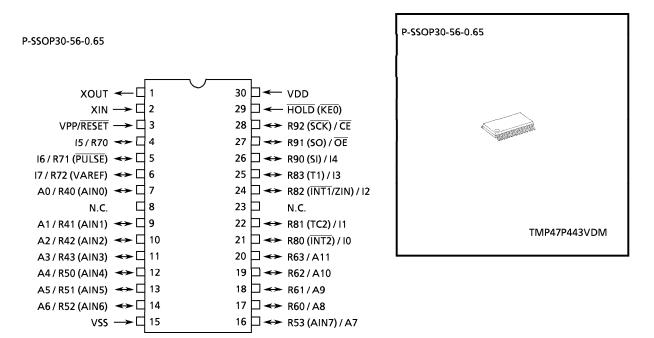
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 making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
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 The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments medical instruments. transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.

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Pin Assignment (Top View)



Pin Function

The TMP47P443V has MCU mode and PROM mode.

(1) MCU mode

The TMP47C243/443 and the TMP47P443V are pin compatible.

(2) PROM mode

Pin Name	Input / Output	Functions	Pin Name (MCU mode)
A11 to A8			R63 to R60
A7 to A4	Input	Address inputs	R53 to R50
A3 to A0			R43 to R40
17 to 15			R72 to R70
14	I/O	Data inputs / outputs	R90
13 to 10			R83 to R80
CE	Input	Chip Enable input	R92
ŌE	input	Output Enable input	R91
VPP		+ 12.5 V / 5 V (Program supply voltage)	RESET
vcc	Power supply	+ 5 V	VDD
VSS		0 V	VSS
HOLD	Input	PROM mode setting pin. Be fixed to low level.	
XIN	Input	Input the clock from the external oscillator. (6 MHz typ.)	
XOUT	Input	Be pulled down to VSS level. (750 Ω typ.)	

Operational Description

The following is an explanation of hardware configuration and operation in relation to the TMP47P443V. The TMP47P443V is the same as the TMP47C243/443 except that an OTP is used instead of a built-in mask ROM.

1. Operation mode

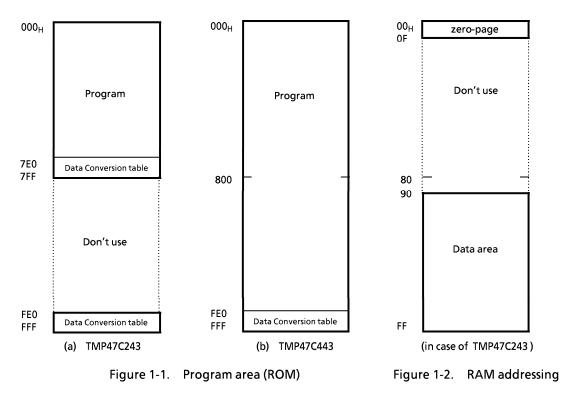
The TMP47P443V has a MCU mode and a PROM mode.

1.1 MCU mode

The MCU mode is set by attaching a resonator between the XIN and Xout pins. Operation in the MCU mode is the same as for the TMP47C243/443. In the TMP47P443V, RC oscillation is impossible.

1.1.1 Program Memory

The program storage area is the same as for the TMP47C443. Data conversion tables must be set in two locations when using the TMP47P443V to check TMP47C243 operation.



1.1.2 Data Memory

The TMP47P443V has 256×4 -bit of data memory (RAM). When the TMP47P443V is used as the TMP47C243 evaluator, programming should be performed assuming that the RAM is assigned to address 00 to 0F_H and 90 to FF_H as show in Figure 1-2. When the BM47C443 (emulator) is used as the TMP47C243 evaluator, it is same.

1.1.3 Input/Output Circuitry

(1) Control pins

TMP47P443V is the same as code SA or SG. In the TMP47P443V, RC oscillation is impossible. Connecting the resonator is required when using as evaluator of I/O code SD.

(2) I/O Ports

The input/output circuit except pin R72 of the TMP47P443V is the same as the TMP47C243/443. In the TMP47P443V, port option (code SA, SD or SG) of pin R72 is programably selectable.

R72 or VAREF is selected by command register (bit3 of the OP0E). That should be executed over head part on the program. This bit data become dummy data at the TMP47C243/443. An undefined value is read from bit 2 of the IP07 with an input instruction when VAREF is selecting as the AD converter analog reference voltage.

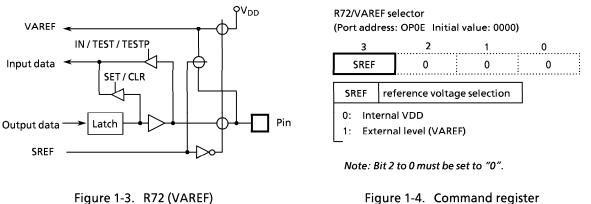


Figure 1-3. R72 (VAREF)

1.2 PROM mode

The PROM mode is set by inputting the external clock to the XIN pin when XOUT pin is pulled down to the VSS level. In PROM mode, programs can be written or verified using a general-purpose PROM writer with an adapter socket being attached.

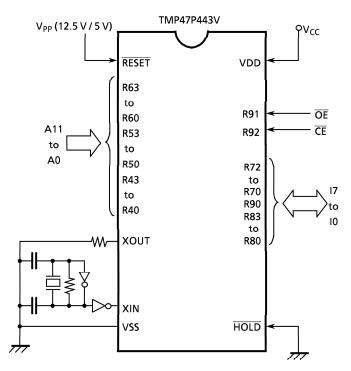


Figure 1-5. Setting for PROM mode

1.2.1 Program Writing

When writing a program, set a ROM type to "57256A" (programming voltage: 12.5 V). Since the TMP47P443V has a 4096 × 8-bit internal PROM (000 to FFF_H), set a stop address of a PROM writer to "FFF_H". For a general-purpose PROM writer, use the writer which does not have or can release an electric signature mode.

Note: When the data written to OTP is same as the data of PROM programmer, there is the possibility that the security writing can not be executed, which is depended on the types of PROM programmers.

In this case, set the data of PROM programmer to "00" and execute the security writing after writing the data to OTP.

1.2.2 High Speed Programming Mode

The program time can be greatly decreased by using this high speed programming mode. The device is set up in the high speed programming mode when the programming voltage (+ 12.5 V) is applied to the V_{PP} terminal with V_{CC} = 6 V and $\overline{CE} = V_{IH}$.

The programming is achieved by applying a single low level 1ms pulse the CE input after addresses and data are stable. Then the programmed data is verified by using Program Verify Mode.

If the programmed data is not correct, another program pulse of 1ms is applied and then programmed data is verified. This should be repeated until the program operates correctly (max. 25 times).

After correctly programming the selected address, one additional program pulse with pulse width 3 times that needed for programming is applied.

When programming has been completed, the data in all addresses should be verified with $V_{CC} = V_{PP} = 5 V$.

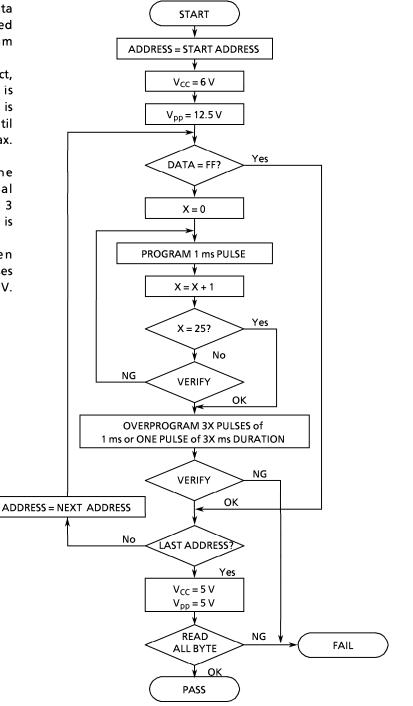


Figure 1-6. Flowchart

Electrical Characteristics

Absolute Maximum Ratings

Absolute Maximum Ratings] (\$55 -					
Parameter	Symbol	Pins	Pins		Unit	
Supply Voltage	V _{DD}			– 0.3 to 6.5	V	
Program Voltage	V _{PP}	RESET / VPP pin		– 0.3 to 13.0	V	
Input Voltage	V _{IN}			– 0.3 to V _{DD} + 0.3	V	
Output Voltage	V _{OUT}			- 0.3 to V _{DD} + 0.3	v	
	I _{OUT1}	Port R5, R6		30	mA	
Output Current (Per 1 pin)	I _{OUT2}	Port R4, R7, R8, R9		3.2		
Output Current (Total)	ΣI_{OUT}	Port R4, R5, R6, R7, R8, R9		120	mA	
			DIP	300		
Power Dissipation [Topr = 70°C]	PD		SOP	180	mW	
			SSOP	145		
Soldering Temperature (time)	Tsld			260 (10 s)	°C	
Storage Temperature	Tstg			– 55 to 125	°	
Operating Temperature	Topr			– 30 to 70	°C	

(Vcc = 0 V)

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant. Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

Recommended Operating Conditions

 $(V_{SS} = 0 V, Topr = -30 to 70^{\circ}C)$

Parameter	Symbol	Pins	Conditions	Min	Max	Unit
			fc = 8.0 MHz	2.7		
Supply Voltage	V_{DD}		fc = 4.2 MHz	2.2	5.5	V
			In the HOLD mode	2.0		
	V _{IH1}	Except Hysteresis Input	In the normal	V _{DD} × 0.7		
Input High Voltage	V _{IH2}	Hysteresis Input	operating area	V _{DD} × 0.75	V _{DD}	V
	V _{IH3}		In the HOLD mode	V _{DD} × 0.9		
	V _{IL1}	Except Hysteresis Input	In the normal		$V_{DD} \times 0.3$	
Input Low Voltage	V _{IL2}	Hysteresis Input	operating area	0	V _{DD} × 0.25	V
	V _{IL3}		In the HOLD mode		V _{DD} × 0.1	
Clock Frequency	fc		$V_{DD} = 2.7 \text{ to } 5.5 \text{ V}$		8.0	
	TC	XIN, XOUT	V _{DD} = 2.2 to 5.5 V	0.4	4.2	MHz

Note: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

DC Characte	eristics		$(V_{SS} = 0 V, Topr =$	– 30 to 70°C)					
Parameter	Symbol	Pins		Conditions	Min	Тур.	Max	Unit	
Hysteresis Voltage	V _{HS}	Hyst	eresis Input		-	0.7	-	v	
	I _{IN1}	RESE	T, HOLD						
Input Current	I _{IN2}	Ope	n drain output ports	$V_{DD} = 5.5 V, V_{IN} = 5.5 V / 0 V$	-	-	±2	μΑ	
Input Resistance	R _{IN}	RESE	T		100	220	450	kΩ	
Output Leakage Current	I _{LO}	Ope	n drain output ports	V _{DD} = 5.5 V, V _{OUT} = 5.5 V	_	-	2	μΑ	
Output Low		_		$V_{DD} = 4.5 V, I_{OL} = 1.6 mA$	-	_	0.4		
Voltage	V _{OL}	V _{OL} Port	R4, R7, R8, R9	$V_{DD} = 2.2 \text{ V}, \ I_{OL} = 20 \ \mu \text{A}$	-	_	0.1	V	
Output Low Current	I _{OL1}	Port	R5, R6	$V_{DD} = 4.5 V, V_{OL} = 1.0 V$	7	20	_	mA	
Supply Current				$V_{DD} = 5.5 V$, fc = 4 MHz	-	2	4		
Supply Current (in the Normal operating mode)	I _{DD}	I _{DD}		$V_{DD} = 3.0 V$, fc = 4 MHz	-	1	2	mA	
				$V_{DD} = 3.0 V$, fc = 400 kHz	_	0.5	1	1	
Supply Current (in the HOLD operating mode)	I _{DDH}			V _{DD} = 5.5 V	-	0.5	10	μΑ	

Note 1: Typ. values show those at Topr = 25° C, $V_{DD} = 5 V$.

Note 2: Input Current I_{IN1} : The current through resistor is not included.

Note 3: Supply Current: The analog supply current (I_{REF}) is not included.

Note 4: Supply Current: $V_{IN} = 5.3 \text{ V} / 0.2 \text{ V} (V_{DD} = 5.5 \text{ V}), 2.8 \text{ V} / 0.2 \text{ V} (V_{DD} = 3.0 \text{ V})$

AD Conversion Characteristics

 $(Topr = -30 \text{ to } 70^{\circ}\text{C})$

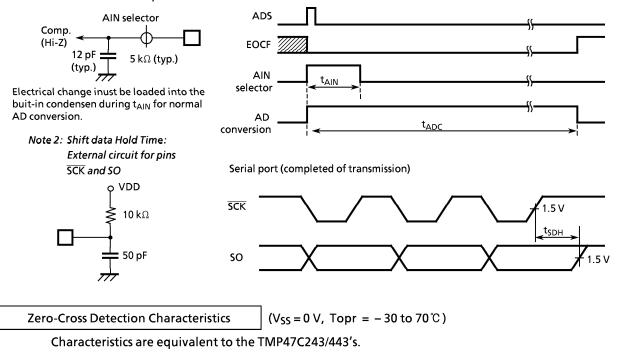
Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Analog Reference Voltage	V _{AREF}		V _{DD} – 1.5	_	V _{DD}	v
Analog Reference Voltage Range	ΔV_{AREF}	V _{AREF} – V _{SS}	2.7	_	_	V
Analog Input Voltage	V _{AIN}		V _{SS}	_	V _{DD}	v
Analog Supply current	I _{REF}		—	0.5	1.0	mA
Nonlinearity Error		N 27. 55.	—	-	± 1	
Zero Point Error		$V_{DD} = 2.7 \text{ to } 5.5 \text{ V},$	_	_	± 1	LSB
Full Scale Error		$V_{AREF} = V_{DD} \pm 0.001 V$	_	_	± 1	
Total Error		$V_{SS} = \pm 0.001 V$	_	_	± 2	

 $(V_{SS} = 0 V, Topr = -30 to 70^{\circ}C)$

Parameter	Symbol	Co	nditions	Min	Тур.	Max	Unit
			V _{DD} = 2.7 to 5.5 V	1.0		20	
Instruction Cycle Time	tcy		V_{DD} = 2.2 to 5.5 V	1.9	-		μS
High level clock pulse width			$V_{DD} \ge 2.7 V$	60			
	t _{WCH}	For external clock (XIN input)	V _{DD} <2.7 V	120		_	
Low level clock pulse width			$V_{DD} \ge 2.7 V$	60			ns
	t _{WCL}		V _{DD} <2.7 V	120			
AD Conversion Time	t _{ADC}			-	24 tcy	_	<i></i> c
AD Sampling Time	t _{AIN}			-	2 tcy	_	μS
Shift data Hold Time	t _{SDH}			0.5 tcy – 0.3	_	_	μs

Note 1: AD conversion timing: Internal circuit for pins AIN0 to 7





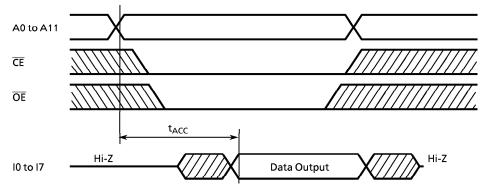
Recommended Oscillating Conditions $(V_{SS} = 0 \text{ V}, V_{DD} = 2.2 \text{ to } 5.5 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Recommended oscillating conditions of the TMP47P443V are equal to the TMP47C243/443's but RC oscillation is impossible.

DC/AC Characteristics (V_{SS} = 0 V)

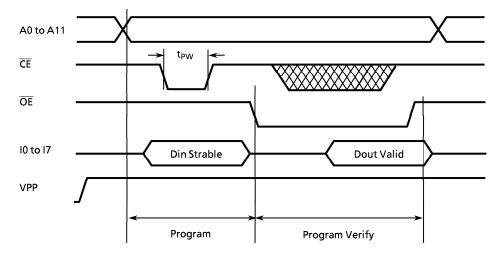
(1) Read Operation

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Output Level High Voltage	V _{IH4}		V _{CC} × 0.7	-	V _{cc}	v
Output Level Low Voltage	V _{IL4}		0	-	V _{CC} × 0.3	v
Supply Voltage	V _{cc}		4.75	_	6.0	v
Programming Voltage	V _{PP}		4.75	-	6.0	v
Address Access Time	t _{ACC}	V _{CC} = 5.0 ± 0.25 V	0	_	350	ns



(2) High Speed Programming Operation

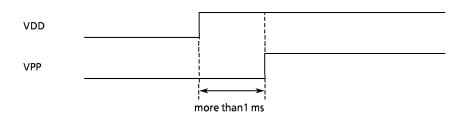
Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Input High Voltage	V _{IH4}		V _{CC} × 0.7	-	V _{cc}	V
Input Low Voltage	V _{IL4}		0	-	V _{CC} × 0.3	v
Supply Voltage	V _{CC}		4.75	-	6.0	v
V _{PP} Power Supply Voltage	V _{PP}		12.0	12.5	13.0	v
Programming Pulse Width	t _{PW}	V _{CC} = 6.0 ± 0.25 V	0.95	1.0	1.05	ms



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Note: There are some PROM programmer types which cannot program OTP.

In TMP47P443V, VPP pin is also used as RESET pin. To set a mode, REST/VPP pin must be set to "low" during 1 ms and more after the rising of power-on and the rising of VDD electrical power.



Recommended EPROM programmer

TYPE R4945 (ADVANTEST) UNISITE (DATA I/O) AF – 9706 (ANDO) PECKER – 11 (AVAL DATA)